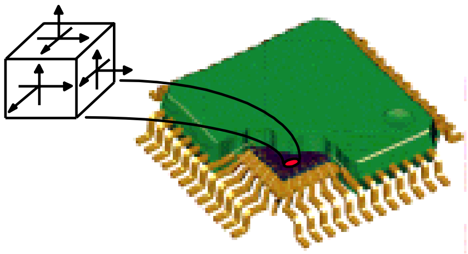
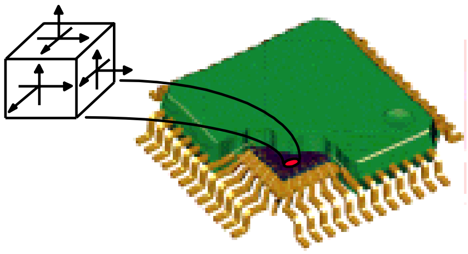


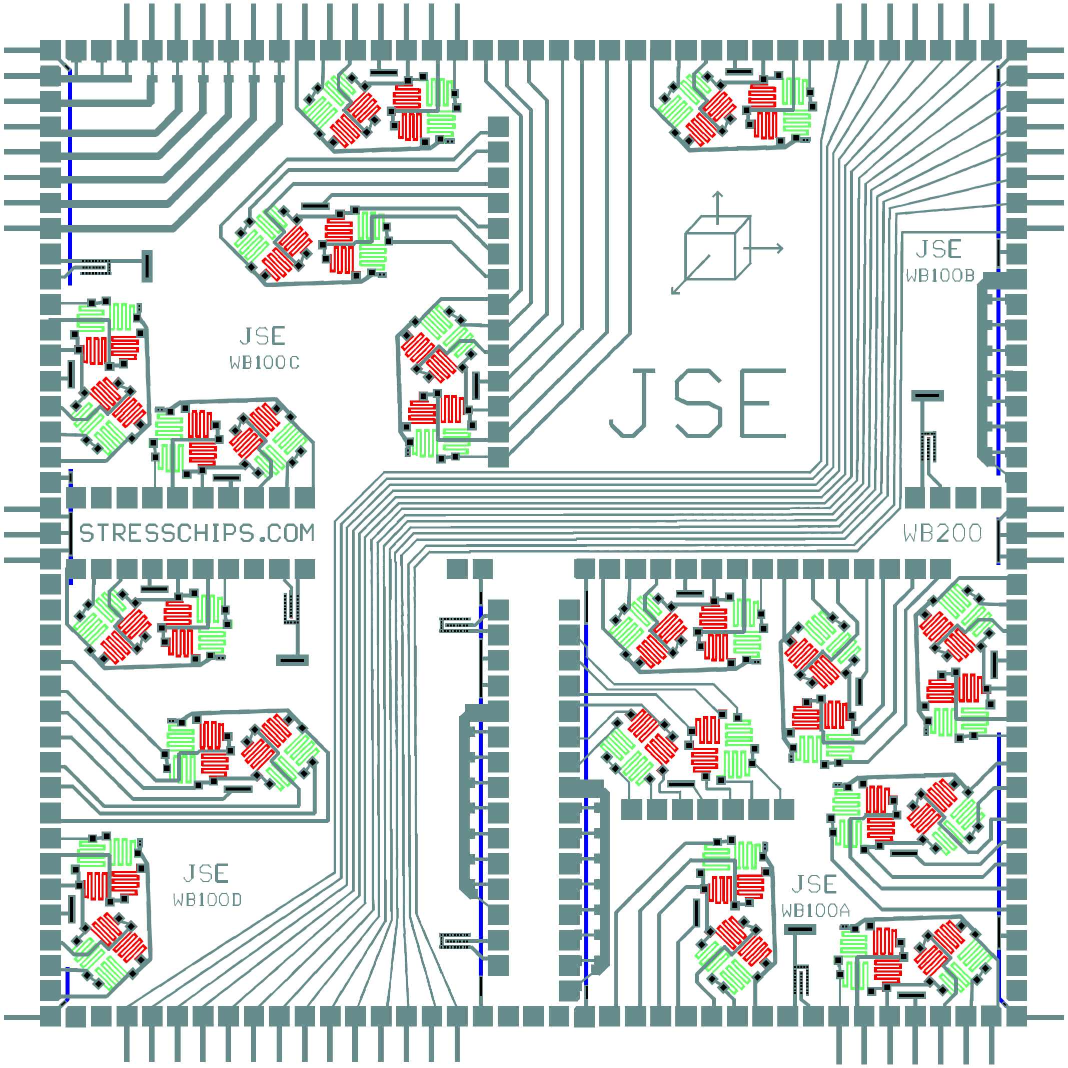
STRESS TEST CHIPS
WIRE BOND DIE

JS Engineering, L.L.C.
P. O. Box 2084
Auburn, AL 36831-2084
USA

www.stresschips.com



WIRE BOND TEST DIE



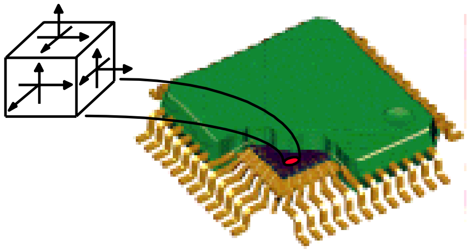
WB200

- 5 x 5 mm Die
- Chip ID (Fuses)
- 10 Rosettes
- Sub Surface Heater
- Diode Temperature Sensors

WB100A

- 2.5 mm x 2.5 mm Die
- Chip ID
- 7 Rosettes
- Sub Surface Heater
- Diode Temperature Sensors

WIRE BOND TEST DIE

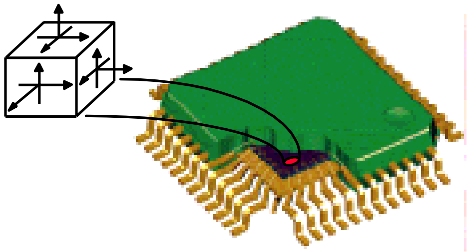


WB400

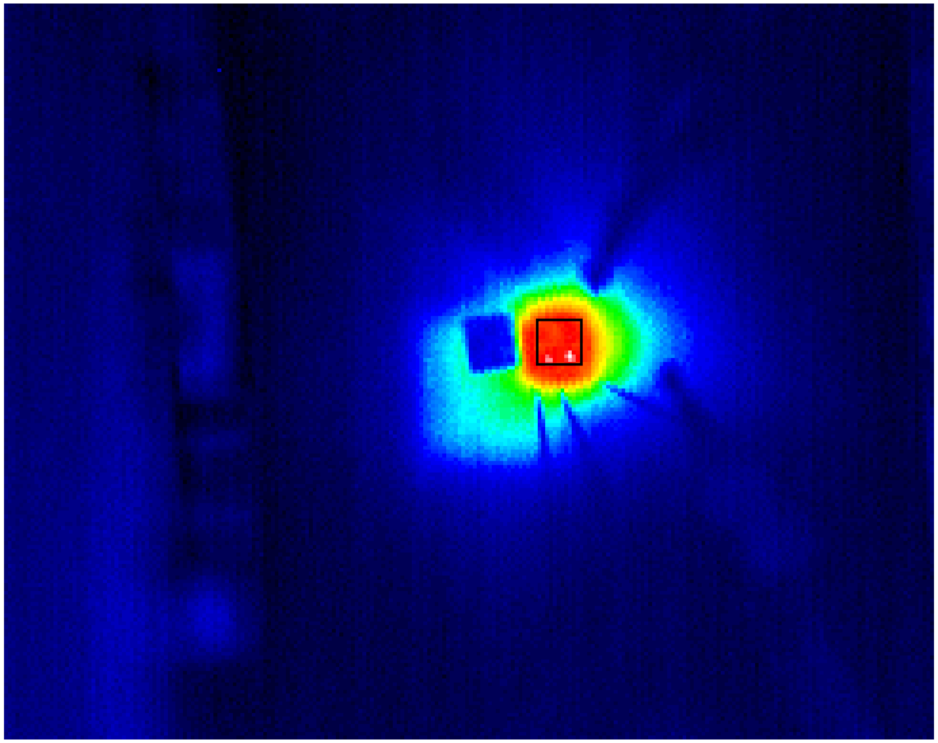
- 2 x 2 Array of the WB200
- 10 x 10 mm Die
- Chip ID
- 23 Rosettes
- Sub Surface Heater
- Diode Temperature Sensors

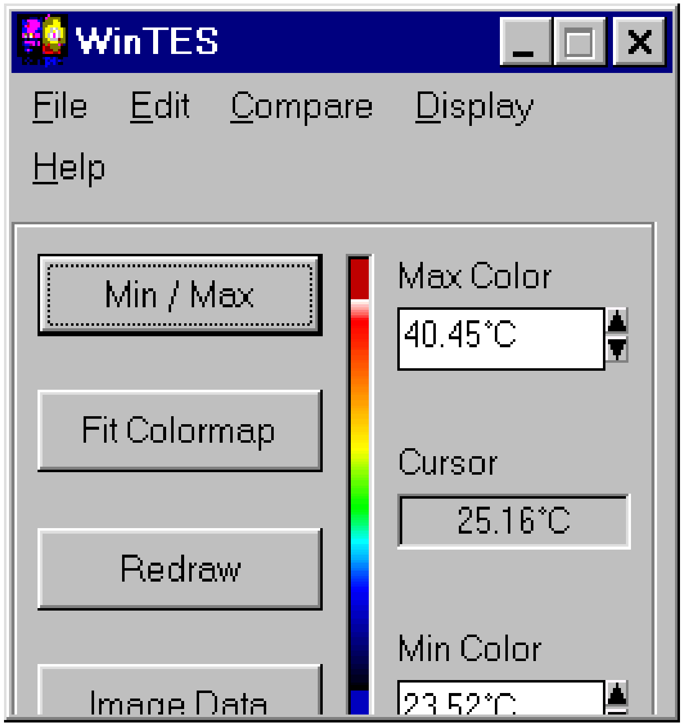
THERMAL TEST

Wire Bond Test Chip



Chip Heater Test
Voltage = 3 V, Current = 0.062 A, Resistance = 50.6 Ω





Max Color 40.45°C

Cursor 25.16°C

Min Color 23.52°C